

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPG20N10S4-36A	**Issued**	27. April 2022
MA#	MA005728691		
Package	PG-TDSON-8-10	**Weight***	99.43 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	1.057	1.06	1.06	10629	10629
chip_2	inorganic material	silicon	7440-21-3	1.057	1.06	1.06	10629	10629
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		132	
	non noble metal	iron	7439-89-6	0.044	0.04		440	
	non noble metal	copper	7440-50-8	43.681	43.97	44.02	439336	439908
wire	non noble metal	aluminium	7429-90-5	0.849	0.85	0.85	8535	8535
encapsulation	organic material	carbon black	1333-86-4	0.091	0.09		914	
	plastics	epoxy resin	-	6.454	6.49		64911	
	inorganic material	silicondioxide	60676-86-0	38.905	39.13	45.71	391292	457117
leadfinish	non noble metal	tin	7440-31-5	1.396	1.40	1.40	14045	14045
plating	inorganic material	phosphorus	7723-14-0	0.001			14	
	non noble metal	nickel	7440-02-0	0.603	0.61	0.61	6066	6080
solder	non noble metal	tin	7440-31-5	0.051	0.05		518	
	noble metal	silver	7440-22-4	0.064	0.06		647	
	non noble metal	lead	7439-92-1	2.457	2.47	2.58	24713	25878
heatspreader	inorganic material	phosphorus	7723-14-0	0.001			8	
	non noble metal	iron	7439-89-6	0.003			27	
	non noble metal	copper	7440-50-8	2.699	2.71	2.71	27144	27179
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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